

Glass Passivated Ultrafast Rectifier

Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
V_{RRM}	100 V to 200 V
I_{FSM}	50 A
t_{rr}	35 ns
V_F	0.95 V
I_R	2.0 μ A
T_j max.	175 °C


DO-204AC (DO-15)

*Patented**

* Glass Encapsulation
technique is covered by
Patent No. 3,996,602,
brazed-lead assembly
to Patent No. 3,930,306

Features

- Cavity-free glass-passivated junction
- Ultrafast reverse recovery time
- Low forward voltage drop
- Low leakage current
- Low switching losses, high efficiency
- High forward surge capability
- Meets environmental standard MIL-S-19500
- Solder Dip 260 °C, 40 seconds



Mechanical Data

Case: DO-204AC, molded epoxy over glass body
Epoxy meets UL-94V-0 Flammability rating

Terminals: Matte tin plated leads, solderable per
J-STD-002B and JESD22-B102D
E3 suffix for commercial grade, HE3 suffix for high
reliability grade (AEC Q101 qualified)

Polarity: Color band denotes cathode end

Typical Applications

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer, computer, automotive and Telecommunication

Maximum Ratings

$T_A = 25$ °C unless otherwise specified

Parameter	Symbol	FGP20B	FGP20C	FGP20D	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	100	150	200	V
Maximum RMS voltage	V_{RMS}	70	105	140	V
Maximum DC blocking voltage	V_{DC}	100	150	200	V
Maximum average forward rectified current 0.375" (9.5 mm) lead length at $T_L = 75$ °C	$I_{F(AV)}$	2.0			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	50			A
Operating junction and storage temperature range	T_J, T_{STG}	- 65 to + 175			°C

FGP20B thru FGP20D

Vishay Semiconductors



Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Test condition	Symbol	FGP20B	FGP20C	FGP20D	Unit
Maximum instantaneous forward voltage	at 2.0 A	V_F		0.95		V
Maximum DC reverse current at rated DC blocking voltage	$T_A = 25^\circ\text{C}$ $T_A = 100^\circ\text{C}$	I_R		2.0 50		μA
Maximum reverse recovery time	at $I_F = 0.5 \text{ A}$, $I_R = 1.0 \text{ A}$, $I_{rr} = 0.25 \text{ A}$	t_{rr}		35		ns
Typical junction capacitance	at 4.0 V, 1 MHz	C_J		45		pF

Thermal Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	FGP20B	FGP20C	FGP20D	Unit
Typical thermal resistance ^(1, 2)	$R_{\theta JA}$ $R_{\theta JL}$	60	20		$^\circ\text{C}/\text{W}$

Notes:

- (1) Thermal resistance from junction to ambient 0.375" (9.5 mm) lead length mounted on P.C.B. with 0.5 x 0.5" (12 x 12 mm) copper pads.
- (2) Thermal resistance from junction to lead at 0.375" (9.5 mm) lead length with both leads attached to heatsinks

Ratings and Characteristics Curves

$(T_A = 25^\circ\text{C}$ unless otherwise specified)

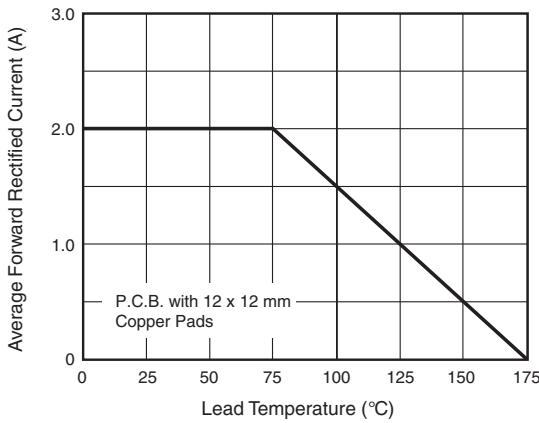


Figure 1. Maximum Forward Current Derating Curve

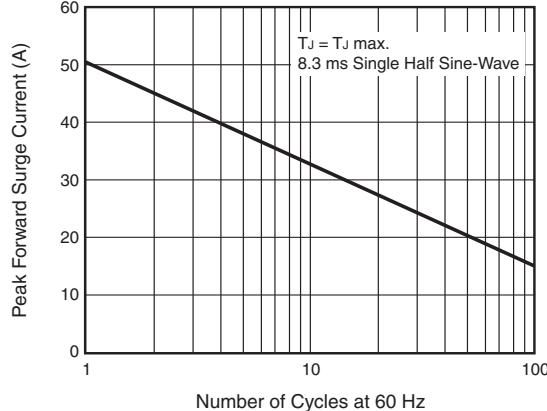


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

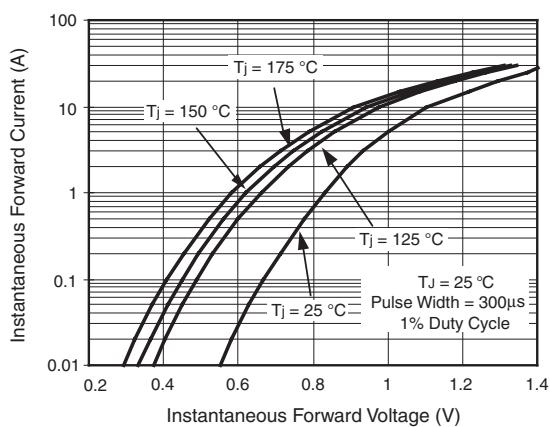


Figure 3. Typical Instantaneous Forward Characteristics

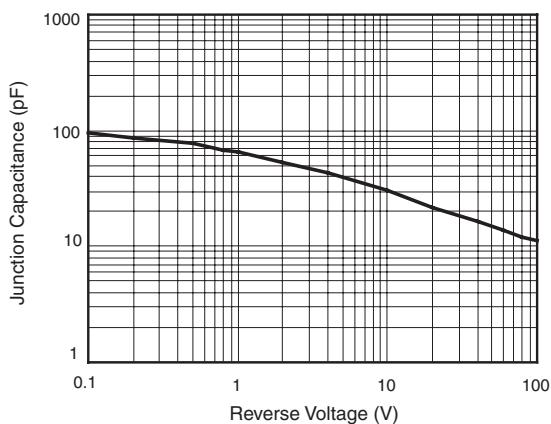


Figure 5. Typical Junction Capacitance

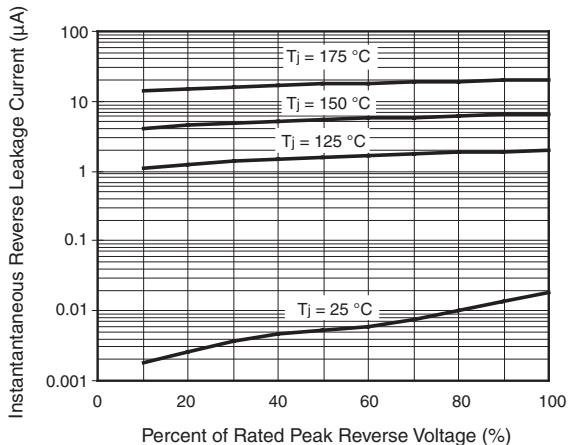


Figure 4. Typical Reverse Leakage Characteristics

Package outline dimensions in inches (millimeters)

